



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20190121001.0
Datasheet for TS3A5017
Information Only**

Date: January 29, 2019
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TS3A5017PWR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190121001.0	PCN Date:	January 29, 2019
Title:	Datasheet for TS3A5017		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.



TS3A5017

SCDS188G – JANUARY 2005 – REVISED JANUARY 2019

Changes from Revision F (October 2018) to Revision G

Page

- Changed *Feature* From: 2000-V Human-Body Model To: 1500-V Human-Body Model 1
- Changed the HBM value From: ± 2000 V To: ± 1500 V in the *ESD Ratings*..... 4

The datasheet number will be changing.

Device Family	Change From:	Change To:
TS3A5017	SCDS188F	SCDS188G

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TS3A5017>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TS3A5017D	TS3A5017DBQR	TS3A5017DGVR	TS3A5017DR
TS3A5017PW	TS3A5017PWG4	TS3A5017PWR	TS3A5017PWRG4
TS3A5017RGYR	TS3A5017RGYRG4	TS3A5017RSVR	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com